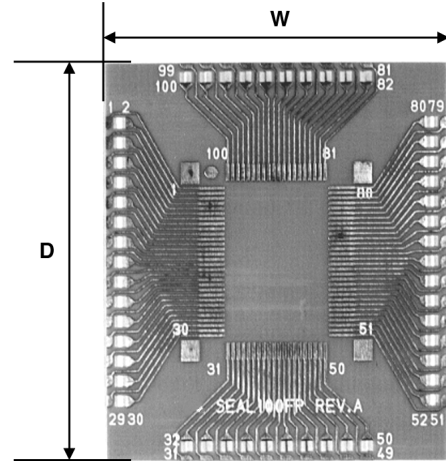# RENESAS

SEAL100FP
Sealed Conversion Board for Converting from 100-pin 0.65mm-pitch QFP (100P6S-A) or LCC (100D0) to 100-pin Standard Pitch

Function

The SEAL100FP is a board for converting the foot pattern of an MCU with a 100-pin 0.65mm-pitch QFP (100P6S-A) or LCC (100D0) package to the standard pitch. Also, this board converts a 100P6S-A or 100D0 IC socket foot pattern to the standard pitch.
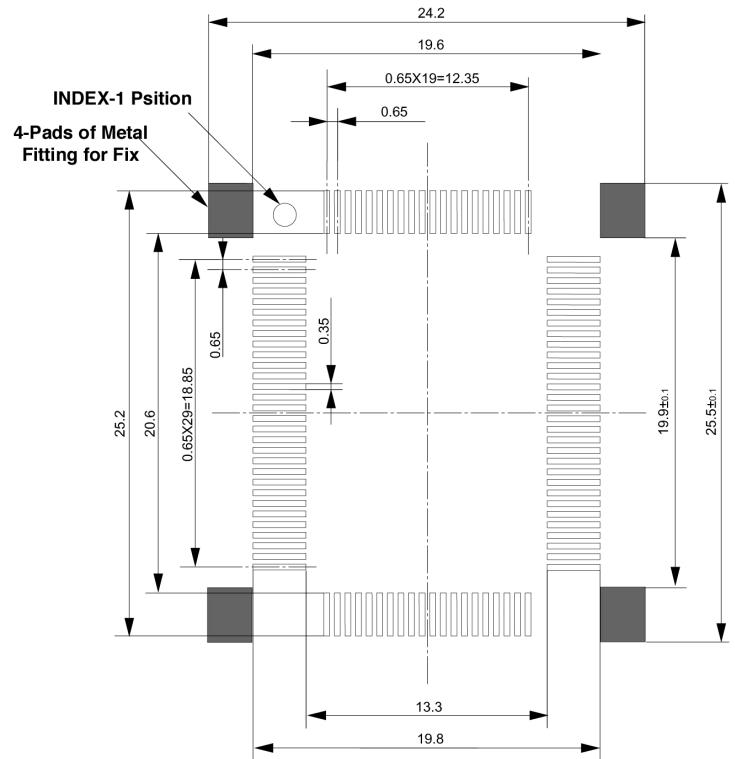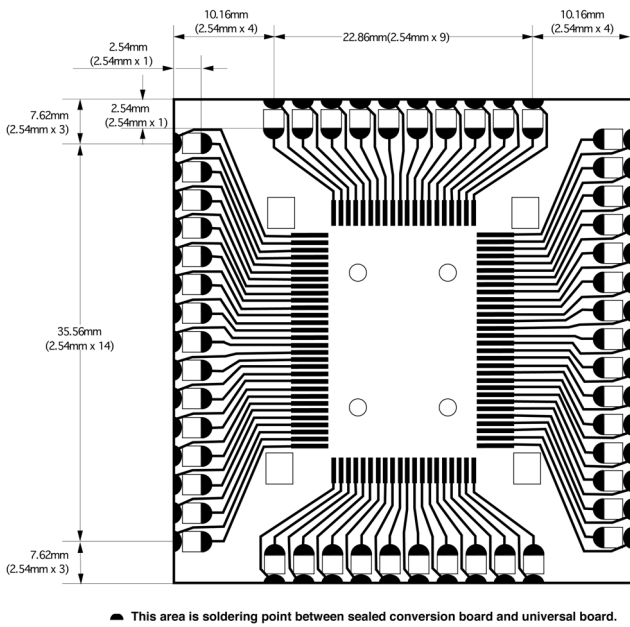
Application

The SEAL100FP is a standard pitch converter that is sealed on its reverse side. It is used to connect an MCU or IC socket with a 100P6S-A or 100D0 package to a standard-pitch universal board, etc. Since there is a mounting pattern for flat packages on the board, it allows mask-ROM or PROM MCUs or 100-pin QFP/LCC IC sockets to be mounted in place directly.

Dimensions

50.80(D)×43.18(W)×0.17(T)mm

Foot Pattern Reference Dimensions

This area is soldering point between sealed conversion board and universal board.

[Ordering Information] See Appendix H "Ordering Information".
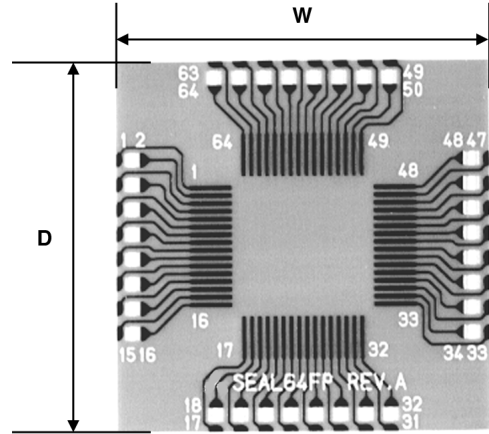
RENESAS

SEAL64FP
Sealed Conversion Board for Converting from 64-pin 0.8mm-pitch QFP
(64P6N-A) or LCC (64D0) to 64-pin Standard Pitch

Function

The SEAL64FP is a board for converting the foot pattern of an MCU
with a 64-pin 0.8mm-pitch QFP (64P6N-A) or LCC (64D0) package
to the standard pitch. Also, this board converts a 64P6N-A or 64D0
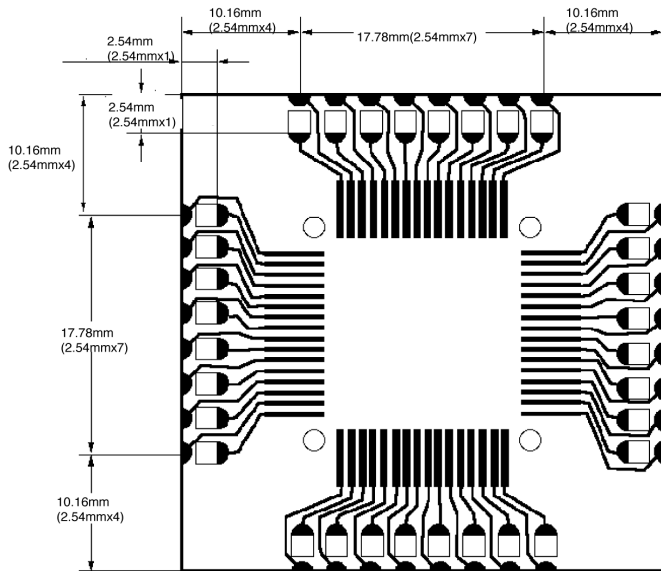IC socket foot pattern to the standard pitch.

Application

The SEAL64FP is a standard pitch converter that is sealed on its
reverse side. It is used to connect an MCU or IC socket with a
64P6N-A or 64D0 package to a standard-pitch universal board, etc.
Since there is a mounting pattern for flat packages on the board, it
allows mask-ROM or PROM MCUs or 64-pin QFP/LCC IC sockets
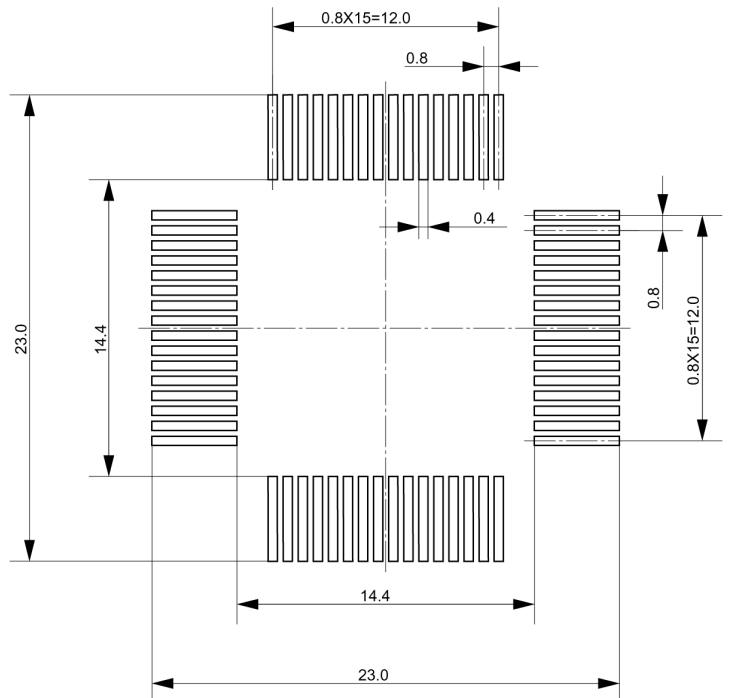to be mounted in place directly.

Dimensions

38.10(D)×38.10(W)×0.17(T)mm

Foot Pattern Reference Dimensions

This area is soldering point between sealed conversion board and universal board.

[Ordering Information] See Appendix H "Ordering Information".
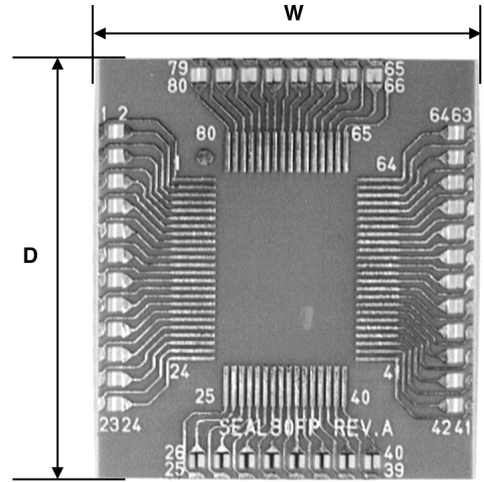
RENESAS

RENESAS

SEAL80FP
Sealed Conversion Board for Converting from 80-pin 0.8mm-pitch QFP
(80P6-B or 80P6N-A) or LCC (80D0) to 80-pin Standard Pitch

Function

The SEAL80FP is a board for converting the foot pattern of an MCU with an 80-pin 0.8mm-pitch QFP (80P6-B or 80P6N-A) or LCC (80D0) package to the standard pitch. Also, this board converts an 80P6-B, 80P6N-A or 80D0 IC socket foot pattern to the standard pitch.
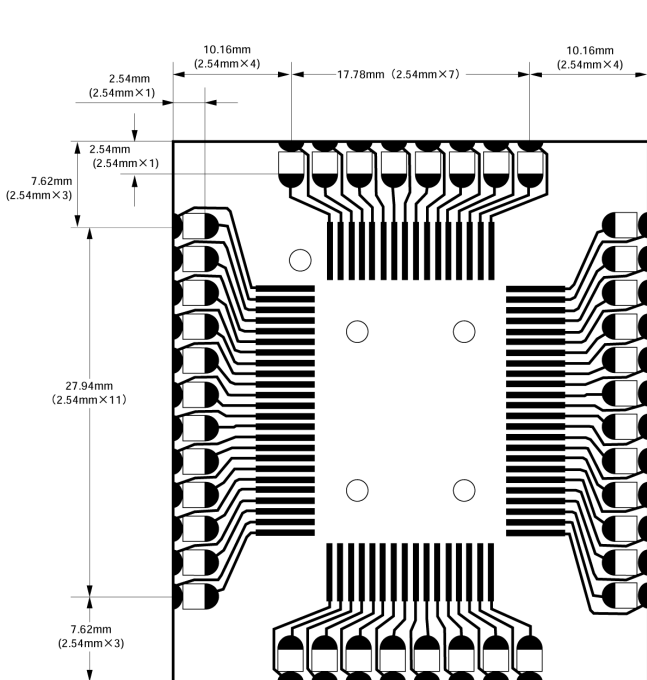
Application

The SEAL80FP is a standard pitch converter that is sealed on its reverse side. It is used to connect an MCU or IC socket with an 80P6-B, 80P6N-A or 80D0 package to a standard pitch universal board, etc. Since there is a mounting pattern for flat packages on the board, it allows mask-ROM or PROM MCUs or 80-pin QFP/LCC IC sockets to be mounted in place directly.
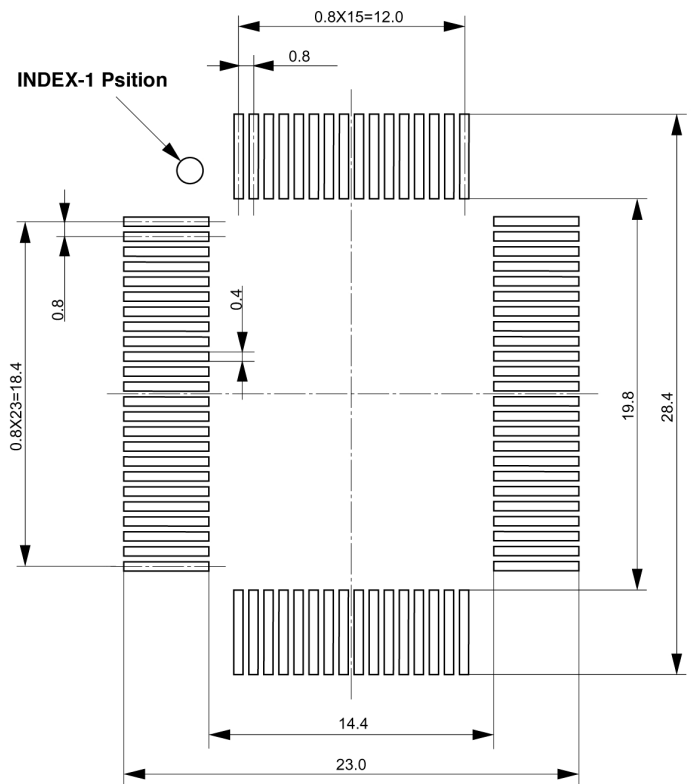
Dimensions

43.18(D)×38.10(W)×0.17(T)mm

Foot Pattern Reference Dimensions

◗ This area is soldering point between sealed conversion board and universal board.

[Ordering Information] See Appendix H "Ordering Information".
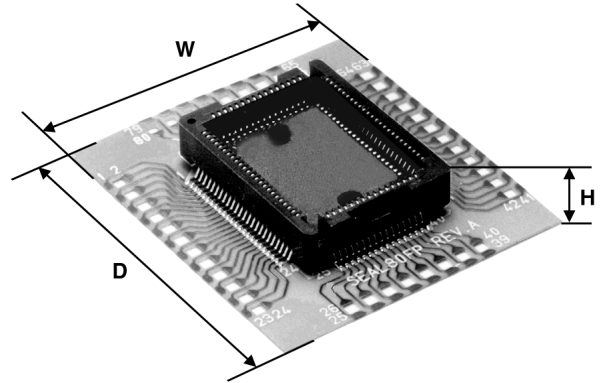
RENESAS

SEAL80FPS

Sealed Conversion Board for Converting from 80-pin 0.8mm-pitch LCC
(80D0) to 80-pin Standard Pitch

Function

The SEAL80FPS is a board for converting the foot pattern of an MCU with an 80-pin 0.8mm-pitch LCC (80D0) package to the standard pitch.
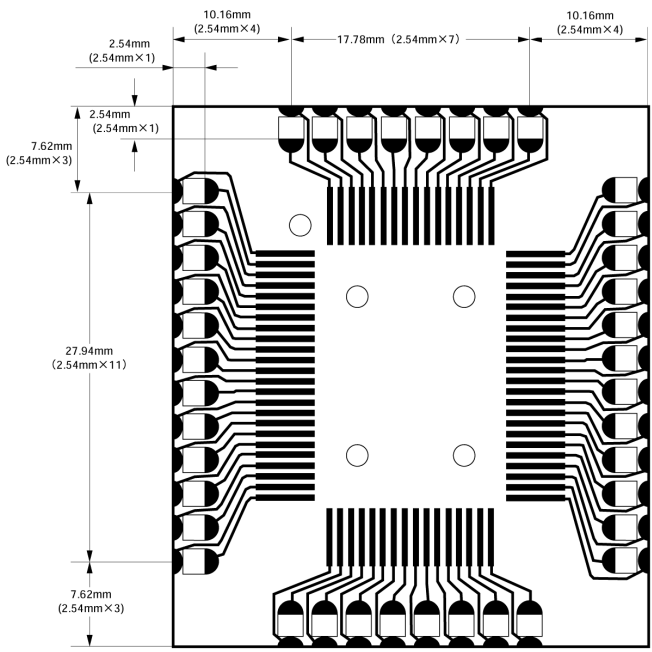
Application

The SEAL80FPS is a standard pitch converter that is sealed on its reverse side. It is used to connect an MCU with an 80D0 package to a standard pitch universal board, etc. The SEAL80FPS has an LCC socket (IC61-0804-046 made by Yamaichi Electronics Co., Ltd.).
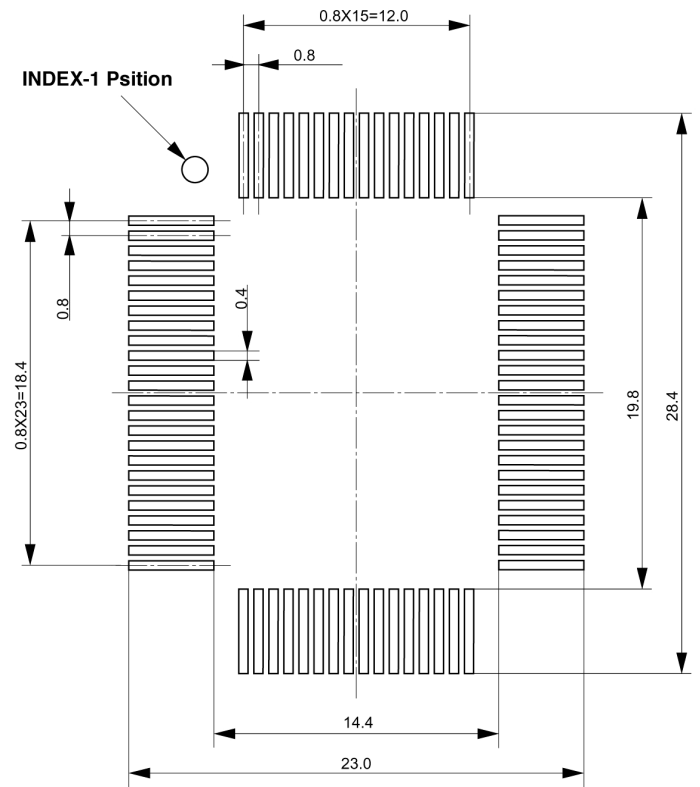
Dimensions

43.18(D)×38.10(W)×6.37(H)mm

Foot Pattern Reference Dimensions

▆ This area is soldering point between sealed conversion board and universal board.

[Ordering Information] See Appendix H "Ordering Information".